

L Number	Hits	Search Text	DB	Time stamp
1	8	waveguide and optics and (silica near microstructure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:13
2	24	silica near microstructure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:19
3	1	(poly with (etch near stop)) same (gold or platinum or alumina or Au or Pt or Al2O3 or "Al.sub.2 O.sub.3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:21
4	230	((etch near stop)) with (gold or platinum or alumina or Au or Pt or Al2O3 or "Al.sub.2 O.sub.3")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:22
5	161	((etch near stop)) with (gold or platinum or alumina or Au or Pt or Al2O3 or "Al.sub.2 O.sub.3") and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:29
6	2	silica near microstructure and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:29
-	1107	((438/778) or (438/787) or (438/761)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/14 10:07
-	220	((planar adj lightwave adj circuit) or (PLC)) or (microelectromechanical or (MEMS)) and (silica or (silicon adj (oxide or dioxide)) or SiO or SiO2 or "SiO.sub.2" or "SiO.sub.x") and RIE and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 16:19
-	38	(MEMS and (dual near damascene))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 16:46
-	6613	(silica or (silicon adj oxide) or SiO or SiO2 or "SiO.sub.2" or "SiO.sub.x" or SiOx) near (etching or etch or etched)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 16:48
-	3	((silica or (silicon adj oxide) or SiO or SiO2 or "SiO.sub.2" or "SiO.sub.x" or SiOx) near (etching or etch or etched)) and ((etch adj stop adj (film or barrier or layer)) near (platinum or Pt or Au or gold or alumina or Al2O3 or AlxOy or "Al.sub.2O.sub.3" or "Al.sub.xO.sub.y" or ((aluminum or aluminium) near oxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 16:52
-	88	(438/764).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 16:57
-	4	(insulating or insulator or isolation or insulated or dielectric) near (different near width)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/11 17:00

-	117	(insulating or insulator or isolation or insulated or dielectric) near (different near thickness)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/07/11 17:21
-	11	5918133.URPN.	USPAT	2002/07/11 17:06
-	8	("4642881" "4651406" "5254489" "5316981" "5330920" "5352618" "5498577" "5501996").PN.	USPAT	2002/07/11 17:13
-	3	(dual adj damascene) near (silica or (silicon adj oxide) or SiO or SiO2 or "SiO.sub.2" or "SiO.sub.x" or SiOx)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/07/11 17:22
-	25	("4900591" "5204141" "5262279" "5302236" "5356515" "5360646" "5486493" "5488015" "5492736" "5559055" "5591677" "5593741" "5660738" "5679608" "5700720" "5789319" "5807785" "5843847" "6054206" "6124641" "6140226" "6147009" "6159871" "6169021" "6287990").PN.	USPAT	2002/07/11 17:25
-	5	((3982967) or (4098618) or ("4356041") or ("4411929") or ("4945068")).PN.	USPAT	2002/07/12 09:14
-	14591	oxide near thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/07/12 08:56
-	0	(oxide near thickness) and ((etch near (layer or mask or film)) near (Al2O3 or "Al.sub.2O.sub.3" or AlxOy or "Al.sub.xO.sub.y" or alumina or platinum or Pt or gold or Au))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/07/12 08:55
-	4	(oxide near thickness) and ((etch near (stop)) near (Al2O3 or "Al.sub.2O.sub.3" or AlxOy or "Al.sub.xO.sub.y" or alumina or platinum or Pt or gold or Au))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/07/12 08:56
-	89	oxide near (different or varying) near thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/07/12 08:57
-	1	("5538912").PN.	USPAT	2002/07/12 09:14
-	11	((hard near mask) near metal) same (SiO2 or SiO or silicon adj (oxide or dioxide) or "SiO.sub.2" or "SiO.sub.x" or silica)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/07/12 10:07
-	23	metal adj hard adj mask	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/12 10:08